

Appl. No : 10/058,473
Amdt. dated : 11/24/03
Reply to Office Action of 09/08/03

Amendments to the Specification:

1) page 9, last paragraph, page 10, first paragraph, please replace this paragraph with the following amended text:

The positioning and cross sections of the passivation layer 12, the layer 14 of polyimide overlying the passivation layer 12 and the mold compound 16 are again highlighted in the completed package that is shown in cross section in Fig. 1c.

Further highlighted are wire interconnects 24, which are conventional bond wires that interconnect pads [[18]] (not shown in the cross section of Fig. 1c), that are provided in the upper surface of die 10 and that are further exposed through openings (not shown in the cross section of Fig. 1c) created through the passivation layer 12, with contact pads (not shown) in the upper surface of the die support medium 20.

It is well known in the art that die support medium 20 may comprise multiple layers of interconnect traces, separated by insulating layers, for further interconnect of die 10 to surrounding electrical circuitry or electrical components.

Appl. No : 10/058,473
Amdt. dated : 11/24/03
Reply to Office Action of 09/08/03

Additionally, the package is frequently completed by attaching contact balls (not shown) to exposed points of contact in the lower surface of interconnect medium 20, making the package a Ball Grid Array package that provides a large number of I/O interconnect points between die 10 and surrounding networks of interconnect (not shown).

2) page 11, last paragraph, page 12, first paragraph, please replace this paragraph with the following amended text:

Specifically shown in the cross section of Fig. 2b is how the layer 28 of polyimide has been patterned and etched, creating openings 29 through the layer 28 of polyimide. These openings can be trenches, as has been shown in the three-dimensional view of Fig. 2b, or can be holes.

The essence of the openings that are created through the layer 28 of polyimide is that the mold compound 16 can now ~~penetrated~~ penetrate into these openings 29, forming a considerably more solid bond between the layer 28 of polyimide and the overlying mold compound 16.

Appl. No : 10/058,473
Amdt. dated : 11/24/03
Reply to Office Action of 09/08/03

An added advantage of the creation of openings 29 is that these openings can be created at no added cost to the process of creating a semiconductor package, since these openings can be created at the same time and as part of creating openings overlying and exposing [[the]] contact pads [[18]] through the layer 28 of polyimide.